





**DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR** 

#### **Features**

- $BV_{CEO} = 50V$ •
- $R_{SAT} = 160 mV$ •
- I<sub>C</sub> = 1A Continuous Collector Current ٠
- Low Equivalent On Resistance
- Low Saturation Voltage •
- SOT23-6 package
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Devices (Note 2) •

#### **Mechanical Data** Case: SOT23-6

•

Case material: Molded Plastic. "Green" Molding Compound. .

C1

R2

F2

- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.018 grams (approximate)

#### Applications

- LCD Backlighting inverter circuits
- Boost functions in DC-DC converters

SOT-223 C2 C1 0 E1 R **B1** C2E1 Top View Device symbol **Pin Configuration** 

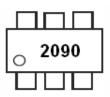
## **Ordering Information**

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTD2090E6TA	2090	7	8	3000

1. No purposefully added lead. Halogen and Antimony Free. Notes:

2. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com.

## **Marking Information**



2090 = Product type Marking Code





#### **DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR**

#### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	50	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Continuous Collector Current (Note 5)	Ic	1	A
Base current	IB	200	mA
Peak Pulse Current	I <sub>CM</sub>	2	А

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation at $T_A = 25^{\circ}C$ (Notes 3 & 6) Linear derating factor	PD	0.90 7.2	W mW /°C
Power Dissipation at $T_A = 25^{\circ}C$ (Notes 3 & 7) Linear derating factor	PD	1.1 8.8	W mW /°C
Power Dissipation at $T_A = 25^{\circ}C$ (Notes 4 & 6) Linear derating factor	PD	1.7 13.6	W mW /°C
Thermal Resistance, Junction to Ambient (Notes 3 & 6)	R <sub>0JA</sub>	139	°C/W
Thermal Resistance, Junction to Ambient (Notes 4 & 6)	R <sub>0JA</sub>	73	°C/W
Thermal Resistance, Junction to Ambient (Notes 3 & 7)	R <sub>0JA</sub>	113	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

3. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions Notes:

4. For a device surface mounted on FR4 PCB measured at < 5sec

5. Repetitive rating – pulse with limited by maximum junction temperature. Refer to transient thermal impedance graph 6. For a device with one active die

7. For a device with two die running at equal power



#### DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	50			V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 8)	V <sub>(BR)CEO</sub>	50			V	$I_{\rm C} = 10 {\rm mA}$
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	5			V	I <sub>E</sub> = 100μA
Collector-Base Cutoff Current	I <sub>CBO</sub>			10	nA	$V_{CB} = 40V$
Collector-Emitter Cutoff Current	ICES			10	nA	$V_{CES} = 40V$
Emitter Cutoff Current	I <sub>EBO</sub>			10	. nA	$V_{EB} = 4V$
DC Current Gain (Note 8)	h <sub>FE</sub>	200 300 200 75 20	420 450 350 130 60			$\begin{split} I_{C} &= 10 \text{mA}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 100 \text{mA}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 500 \text{mA}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 1A, \ V_{CE} = 2 \text{V} \\ I_{C} &= 1.5\text{A}, \ V_{CE} = 2 \text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 8)	V <sub>CE</sub> (SAT)		24 60 120 160	35 80 200 270	mV mV mV mV	$\begin{split} I_{C} &= 100 \text{mA}, \ I_{B} &= 10 \text{mA} \\ I_{C} &= 250 \text{mA}, \ I_{B} &= 10 \text{mA} \\ I_{C} &= 500 \text{mA}, \ I_{B} &= 10 \text{mA} \\ I_{C} &= 1A, \ I_{B} &= 50 \text{mA} \end{split}$
Base-Emitter Saturation Voltage (Note 8)	V <sub>BE(sat)</sub>		940	1100	mV	$I_{\rm C} = 1$ A, $I_{\rm B} = 50$ mA
Base-Emitter Turn-On Voltage (Note 8)	V <sub>BE(ON)</sub>		850	1100	mV	$I_{C} = 1A, V_{CE} = 2V$
Output Capacitance	Cobo		10		pF	V <sub>CB</sub> = 10V. f = 1MHz
Current Gain-Bandwidth Product	f⊤		215		MHz	$V_{CE} = 10V$ , $I_C = 50mA$ f = 100MHz
Turn-On Time	t <sub>on</sub>		150		ns	$V_{CC} = 10V, I_{C} = 1A$
Turn-Off Time	t <sub>off</sub>		425		ns	$I_{B1} = -I_{B2} = 100 \text{mA}$

Notes: 8. Measured under pulsed conditions. Pulse width  $\leq$  300 µs. Duty cycle  $\leq$  2%



#### **DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR**

#### 0.4 0.4 IC/B-50 -29°C 0.3 0.3 IC/19-50 IC/19-50 IC/19-100 S VCE(sat) - (V) -25°C VCE(sat) -0.2 0.2 100% - 150-C 0.1 0.1 0 L 0,**F** Ic - Collector Current (A) Ic - Collector Current (A) VCE(sat) v IC VCE(sat) v IC 1.0 800 ICEP-50 8.0 hee - Typical Gain 600 VBE(sat) - (V) 0.6 400 ΠĦ 0.4 1 ·25% 200 . 100°C 0.2 +150°C 1111 0,E 0 1m 10m IC - Collector Current (A) IC - Collector Current (A) hFE v IC VBE(sat) v IC 10 1.15 Collector Current (A) 0.9 đ VBE(on) - (V) 0.6 00 h 100m 55PC 0.3 125°C 10m + 150°C 100 01 ώ 0 t 10m 100m 100 1m 10m 100m 10 10 Ic - Collector Current (A) VCE - Collector Emitter Voltage (V) Safe Operating Area VBE(on) v IC

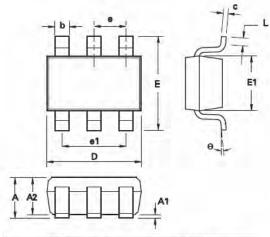
### **Typical Characteristics**





#### DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR

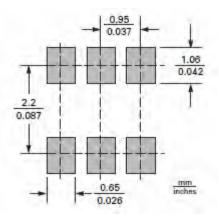
# Package Outline Dimensions



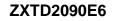
DIM	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
А	0.90	1.45	0.0354	0.0570	
A1	0.00	0.15	0.00	0.0059	
A2	0.90	1.30	0.0354	0.0511	
b	0.35	0.50	0.0078	0.0196	
С	0.09	0.26	0.0035	0.0102	
D	2.70	3.10	0.1062	0.1220	
E	2.20	3.20	0.0866	0.1181	
E1	1.30	1.80	0.0511	0.0708	
L	0.10	0.60	0.0039	0.0236	
е	0.95 REF		0.0374 REF		
e1	1.90	REF	0.0748 REF		
L	0°	30°	0°	30°	

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

## **Suggested Pad Layout**







#### **DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR**

#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devicesor systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2009, Diodes Incorporated

www.diodes.com